

Package 封装 : BGA (Wire-Bond), Leaded (Pb)
 Lead Free 无铅: No 不是

有毒有害物质名称及含量的标识格式						
Table of hazardous substances' name and concentration						
均质材料	铅	镉	六价铬	汞	多溴联苯	多溴联苯醚
Homogeneous Material	Pb	Cd	Cr6+	Hg	PBB	PBDE
Mold compound 模塑料	O	O	O	O	O	O
Substrate 基板	O	O	O	O	O	O
DA epoxy 贴胶	O	O	O	O	O	O
Die, 晶片	O	O	O	O	O	O
Solder ball 焊球	X	O	O	O	O	O
Bond wire 引线	O	O	O	O	O	O

CR-01003-1.1

O: Indicates that the concentration of the hazardous substance in all homogeneous materials in the parts is below the relevant threshold of the SJ/T11363-2006 standard.
 O: 表示该有毒有害物质在该部件所有均质材料中的含量均在SJ/T11363-2006 标准规定的限量要求以下.
 X: Indicates that the concentration of the hazardous substance of at least one of all homogeneous materials in the parts is above the relevant threshold of the SJ/T11363-2006 standard.
 X: 示该有毒有害物质至少在该部件的某一均质材料中的含量超出SJ/T11363-2006 标准规定的限量要求.
 X*: Indicates that the concentration of the hazardous substance of at least one of all homogeneous materials in the parts is above the relevant threshold of the SJ/T11363-2006 standard, but it is exempted by EU ROHS.
 X*: 示该有毒有害物质至少在该部件的某一均质材料中的含量超出SJ/T11363-2006 标准规定的限量要求。但是可以被欧盟(EU ROHS)所豁免的。

Document Revision History	
Date and Document Version	Changes Made
March 2007 v1.1	Updated table to include the symbol explanation
March 2007 v1.0	Initial Release